

ABSTRACT

A laminate comprising a polyimide and a conductor layer, which is obtained by forming at least one conductor layer directly on the surface of a thermoplastic polyimide, is thermally fused by pressurizing and heating to thereby enhance the adhesion strength between the thermoplastic polyimide and the conductor layer. Thus, a laminate having an excellent adhesion strength between a conductor layer and a polyimide film can be obtained without performing any surface roughening treatment or using any adhesive metal layer.